



Technical Data Sheet

StikNPeel™ Rework Stencils

GENERAL DESCRIPTION

StikNPeel™ stencils are made from a custom mylar film with an adhesive backing. Its' backside is coated with a "tacky" adhesive and is backed with a release liner. The StikNPeel™ stencils are pre-scored to allow for easy removal from the release liner.

USES

StikNPeel™ stencils are intended for use as a replacement for the metal stencils used in PCB rework. They are intended for temporary attachment to the PCB using a "tacky" temporary adhesive which is used to keep the stencil coplanar with the PCB and prevent leaching of the solder paste underneath the stencil. It is also used to slide around the stencil until the fine adjustments to the board lands are made. The stencils are used to selectively print solder paste and is available in 4, 5 and 6 mil thicknesses.

FEATURES

Excellent chemical, and impact resistance. The StikNPeel™ stencil is dimensionally stable after being laser machined to the patterns of the PCB lands. Its flexible nature gives it the ability to be used in high-density areas.

PHYSICAL PROPERTIES

THICKNESS	Material	Convention Units	S.I. Units
	Mylar	3.0/4.0/5.0 mils	76/102/127 microns
	Adhesive	1.0 mils	25 microns
	Total	4.0/5.0/6.0 mils	102/127/152 microns

ADHESIVE PERFORMANCE	Steel ASTM D3330 180 degree peel, 72hr dwell	50oz/in	5.4N/100 mm
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STORAGE TEMPERATURES: Store in original packaging at 70° F (21° C) and 50% RH.

APPLICATION TEMPERATURE: Less than 80° F (26.7° C) and 30% RH.

ELONGATION: 135% at break

STORAGE TIME: 2 Years at the proper storage conditions.